TEST REPORT

Reliability Laboratory

Report No.: HC20137/2010
Page: 1 of 6
Date: April 22, 2010

iTech Company LLC
41758 Christy Street,
Fremont CA 94538 USA

The following merchandise was submitted and identified by the vendor as:

Product Description:	20.1 Multimedia LCD Monitor
Style/ Item No.:	WMRM920-PIP/ No. 1
Quantity:	Total 1 set
Testing Period:	Apr. 16, 2010

We have tested the submitted sample(s) as requested and the following results were obtained:

Test Required: (According to client's test specification, please see following sheets in detail.)

1. Thermal Shock Test

Test Results： -PLEASE SEE ATTACHED SHEETS-

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1. Thermal Shock Test:

Test Equipment:

Name	Brand	Model	Serial No.
Programmable Temperature & Humidity Chamber	KSON	THS-D6S-150-LN2	3307
Thermal Shock Chamber	ESPEC	TSD-100	140000083

Lab Environmental Conditions:

Ambient temperature: 25±3℃

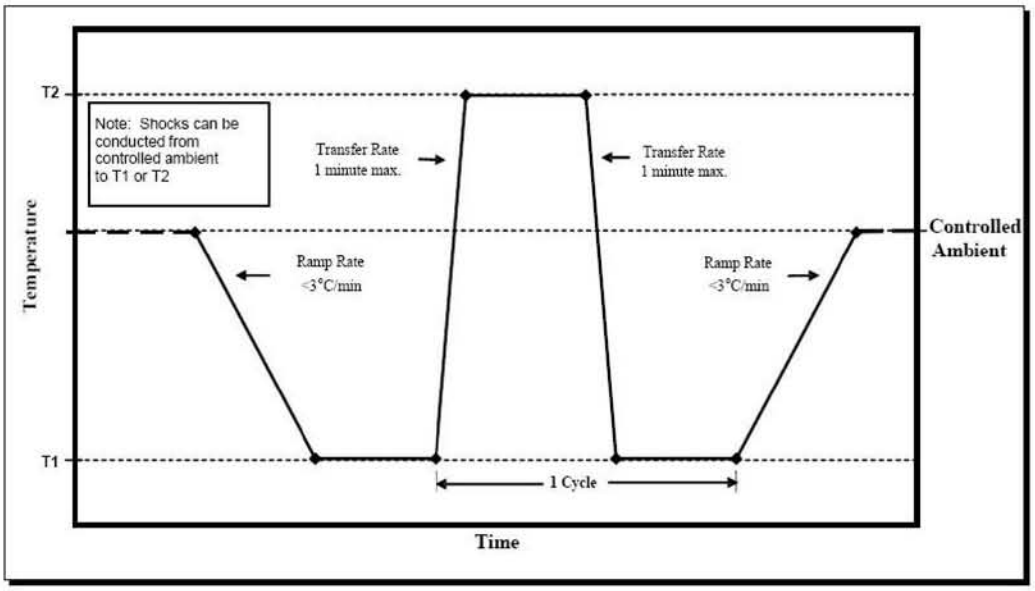
Relative humidity: 55±20%RH

Test Method/ Specification:

Test method: Reference to MIL-STD-810G, Method 503.5 Testing Procedures I-B, Figure 503.5-2. Single cycle shocks.

Temperature: -33 to 63℃±2℃

Test duration: 1 cycle



Test Method/ Specification--Continued:

- Sample condition: Operating
- Examine the appearance of specimen(s) by visual check and perform functional check after this test.
- Functional check: Connect the specimen with rated power then examine whether the display function of specimen could be work normally or not.
- The following procedures provide the basis for collecting the necessary information concerning the materiel in a severe temperature shock environment. According to method 503.5 / procedure I-B / Figure 503.5-2: Single cycle shocks from constant extreme temperature.
- Step1. With the test item in the chamber in its appropriate logistic configuration, adjust the chamber air temperature to the high or low temperature extreme specified in the test plan (T1) at a rate not to exceed 3°C/min . Stabilize the temperature for a period as determined in test plan.
- Step2. Transfer the test item in no more than one minute to an atmosphere at temperature (T2) that will produce the thermal shock specified in the test plan, and stabilize the temperature for a period as determined in test plan.
- Step3. If required in the test plan, evaluate the effects of the thermal shock on the test item to the extent practical.
- Step4. Transfer the test Item back to the T1 environment in no than one minute. Stabilize the temperature for a period and evaluate the thermal shock effects. (if required)
- Step5. Return the test item to standard ambient conditions.
- Step6. Examine the test item and, if appropriate, perform an operational check. Record the results for comparison with pretest data.
- The equipment shall withstand the required temperature shock conditions and shall meet, without any functional damage, all performance requirements after being exposed to 1 cycle of high-low temperatures, as illustrated in Figure 503.5-2. Performance check: Running Window XP with stress software BCM diagnostics Pro version 2.30.

TEST REPORT

Specimen:

Style/ Item No. : WMRM920-PIP/ No. 1

Quantity : total 1 set

Test Result:

Check Item / Style/Item No.	Appearance check (Visual check)	Functional Check & Performance Check
WMRM920-PIP/ No. 1	No visible damage	Normal

Test Photos:

	
1. Appearance of specimen (WMRM920-PIP)	2. Appearance of specimen (WMRM920-PIP)
	
3. Appearance of specimen (WMRM920-PIP)	4. Appearance of specimen (WMRM920-PIP)
	
5. Appearance of specimen (WMRM920-PIP)	6. Appearance of specimen (WMRM920-PIP)

Test Photos--Continued:

7. Thermal Shock Test

8. Thermal Shock Test

9. Thermal Shock Test

10. Thermal Shock Test

11. Functional check

12. Functional check

— — — The End of Test Report — — —